



ES3ABG THRU ES3JBG

Reverse Voltage - 50 to 600 Volts Forward Current - 3.0 Ampere

SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
 - ◆ 250°C/10 seconds at terminals
 - ◆ Glass passivated chip junction

Mechanical Data

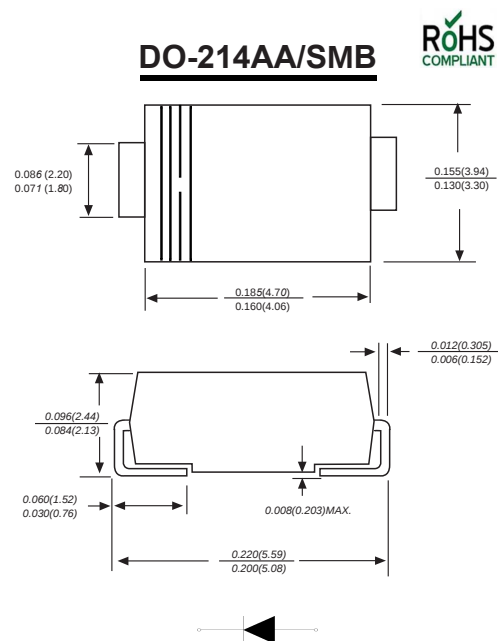
Case : JEDEC DO-214AA/SMB Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.055 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES3ABG	ES3BBG	ES3CBG	ES3DBG	ES3EBG	ES3GBG	ES3JBG	UNITS
Marking Code		MDD ES3AB	MDD ES3BB	MDD ES3CB	MDD ES3DB	MDD ES3EB	MDD ES3GB	MDD ES3JB	
Maximum repetitive peak reverse voltage	V _{RMM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V _{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at TL=55℃	I _(AV)	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	90							A
Maximum instantaneous forward voltage at 3.0A	V _F	1				1.25		1.68	V
Maximum DC reverse current TA=25℃ at rated DC blocking voltage TA=125℃	I _R	5.0 100.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	35							ns
Typical junction capacitance (NOTE 2)	C _J	45.0							pF
Typical thermal resistance (NOTE 3)	RθJA	50.0							℃/W
Operating junction and storage temperature range	T _J , T _{STG}	-55 to +150							℃

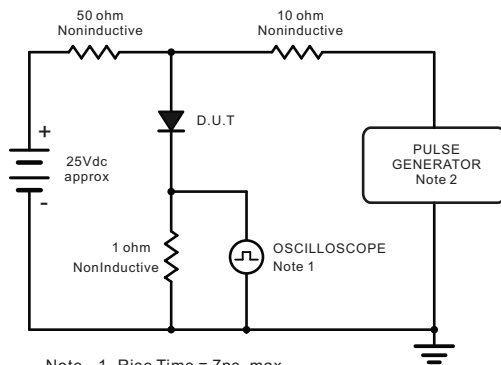
- Note:** 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$
2. P.C.B. mounted with 1.0x1.0" (2.54x2.54cm) copper pad areas.
3. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
4. The typical data above is for reference only.



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Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

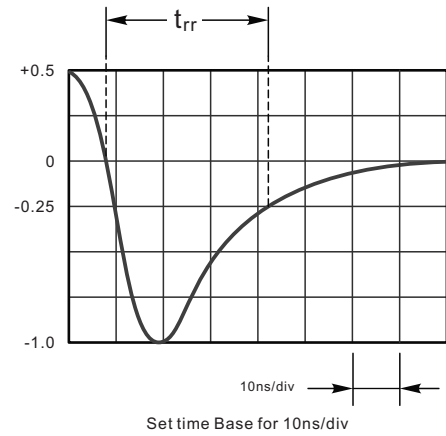


Fig.2 Maximum Average Forward Current Rating

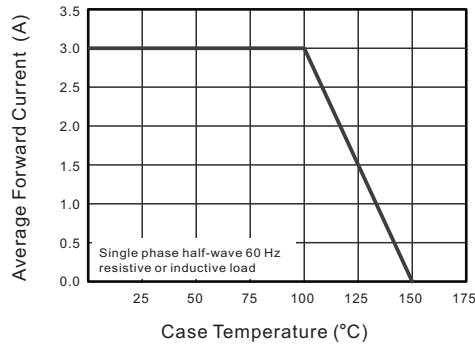


Fig.3 Typical Reverse Characteristics

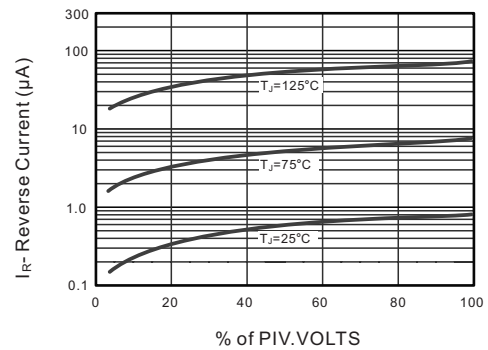


Fig.4 Typical Forward Characteristics

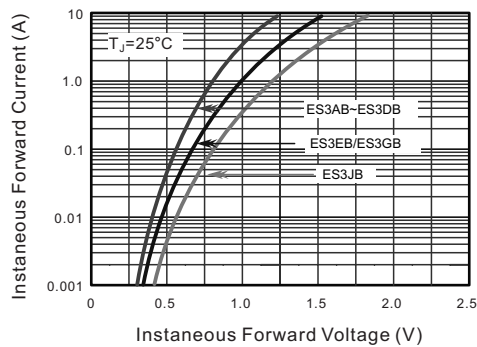


Fig.5 Typical Junction Capacitance

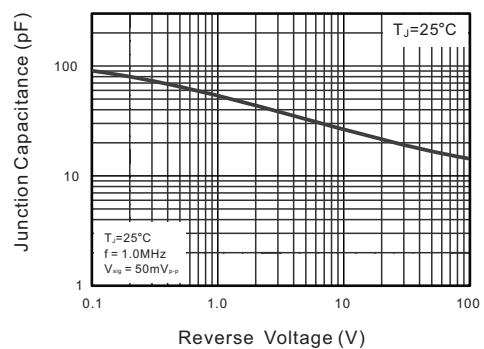
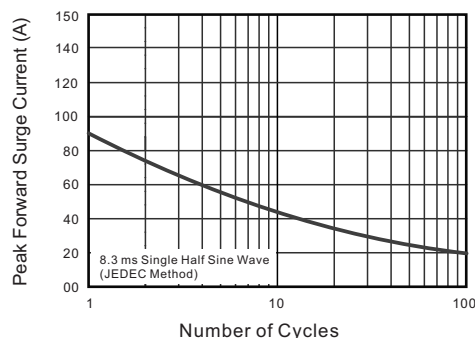


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



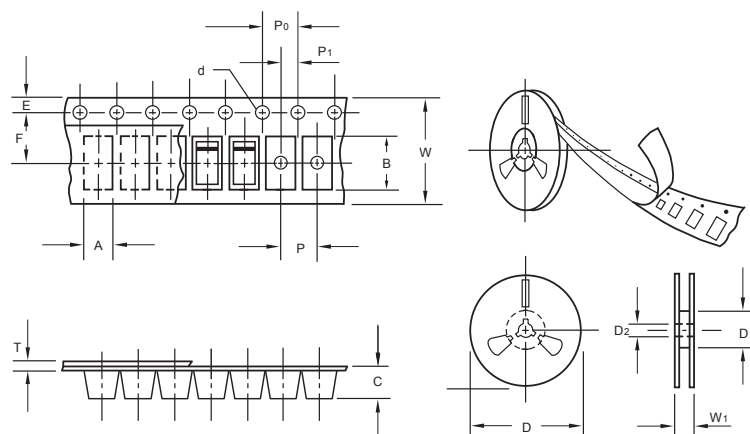
The curve above is for reference only.



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Packing information



unit:mm

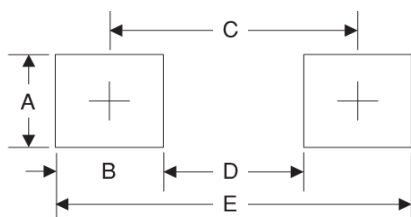
Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1 5.0
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.8	0.110
B	2.4	0.094
C	4.6	0.181
D	2.2	0.086
E	7.0	0.276

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